

10/03/01

THE COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231Docket No. MEG2000-012

J1040 U.S. PTO

09/821546

03/30/01

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: JIN YUAN LEE, CHING CHENG HUANG, MOU SHIANG LIN

For: A STRUCTURE AND MANUFACTURING METHOD OF CHIP SCALE PACKAGE

Enclosed are:

- ☒ 10 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to MEGIC CORPORATION
- ☐ An associate power of attorney ☒ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b) (2) (b) (i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 345.
TOTAL CLAIMS	41 -20=	21	x 9 =	\$ 189.
INDEP CLAIMS	3 -3=	0	x 40 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$ 534.
			ASSIGNMENT	\$40.
			TOTAL	\$574.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 574. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761